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Technical Data Sheet

MODEL NO : S282ANW4

Features :

- 1.0x0.5mm SMT LED, 0.2mm thickness
- Compatible with automatic placement equipment
- Compatible with reflow solder process

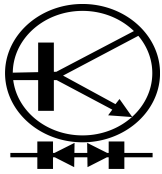
Applications :

- Indicators
- Automotive : backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
InGaN/GaN	White	Yellow

Electrical /Optical Characteristics(Ta=25°C)

Parameter	Test Condition	Symbol	Value			Unit
			Min	Typ	Max	
CIE Coordinates	IF=20mA	λ_d	X:0.2618		Y:0.306	
			X:0.2353		Y:0.3026	
Forward voltage	IF=20mA	VF	2.9	3.1		V
Luminous intensity	IF=20mA	Iv	500	800		mcd
Viewing angle at 50% Iv	IF=10mA	$2\theta_{1/2}$		120		Deg
Reverse current	VR=5V	IR			10	μ A



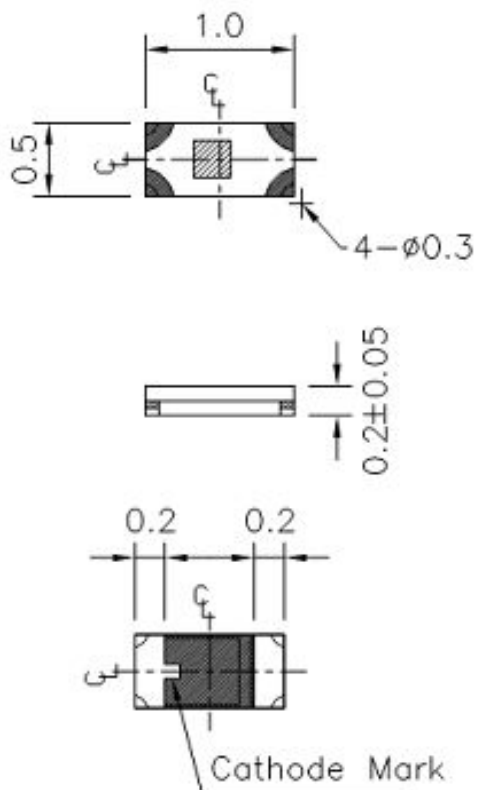
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Absolute Maximum Ratings(Ta=25°C)

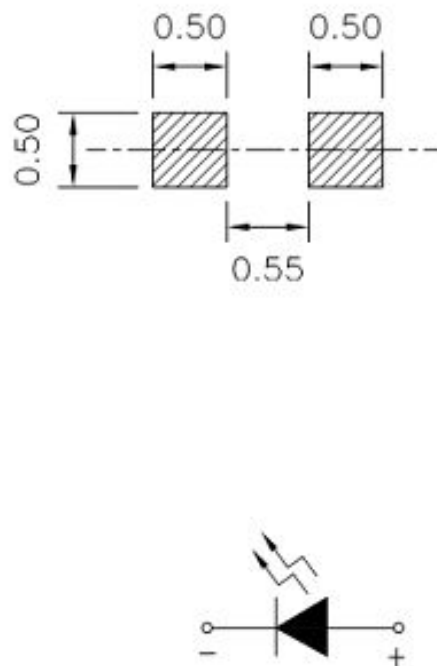
Parameter	Symbol	Value	Unit
Power dissipation	Pd	70	mW
Forward current	I _F	20	mA
Reverse voltage	V _R	5	V
Operating temperature range	Top	-40 ~+80	°C
Storage temperature range	Tstg	-40 ~+85	°C
Peak pulsing current (1/8 duty f=1kHz)	I _{FP}	125	mA

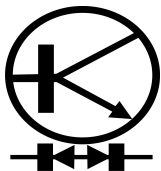
PACKAGING DIMENSIONS (mm):

Package outlines



Recommend Pad Layout

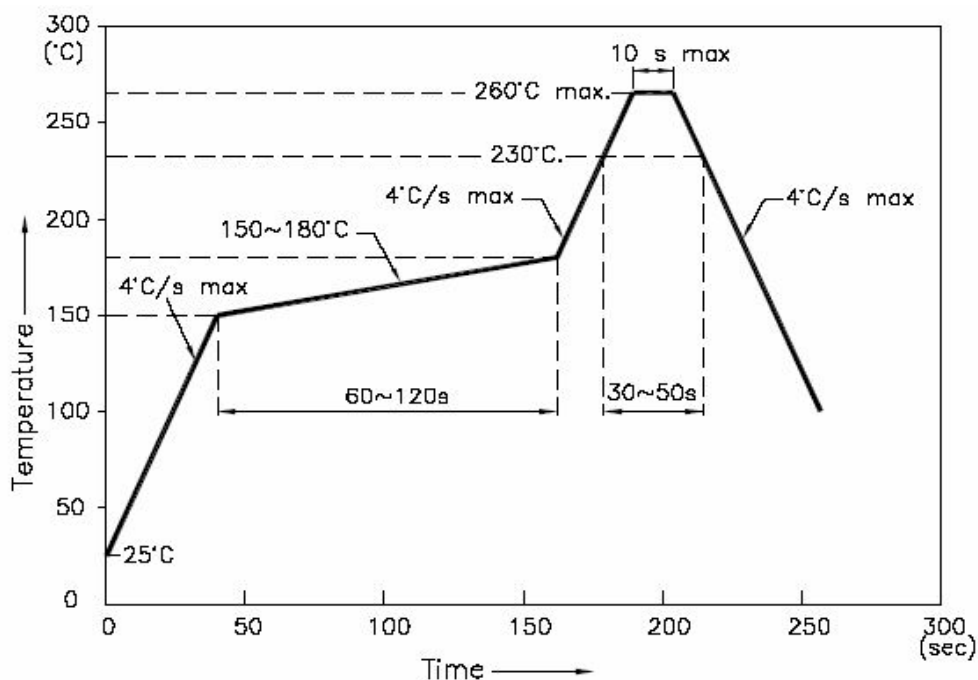




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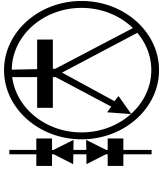
Precautions For Use :
Over- current- proof
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)
Storage
1. The operation of temperature and R.H. are : $5^{\circ}\text{C} \sim 30^{\circ}\text{C}$, 60%R.H. Max.
2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating reagent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date) .
3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

1. We recommend the reflow temperature $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$. the maximum soldering temperature should be limited to 260°C .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.



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■ Soldering iron

Basic spec is $\leq 5\text{sec}$ when 260°C . If temperature is higher, time should be shorter ($+10^{\circ}\text{C} \rightarrow -1\text{sec}$). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C .

- **Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow 、 solder etc.**